

What is claimed is:

1 1. An electronic device, located in surroundings
2 providing an initial airflow, comprising:

3 a host, comprising a housing and a circuit having at least
4 one first heat source and at least one second heat
5 source disposed in the housing;

6 a display unit electronically connected to the circuit;
7 and

8 a heat-dissipating module for providing heat transfer
9 and convection to the surroundings, having at least
10 one conductive assembly disposed on the first heat
11 source to absorb heat transferring from the first
12 heat source and at least one first fan assembly
13 located between the surroundings and the
14 conductive assembly, wherein the first fan
15 assembly introduces the initial airflow of the
16 surroundings into the conductive assembly to form
17 at least one first airflow, and the first airflow
18 passes the second heat source to form at least one
19 second airflow, and temperature ingredient is
20 yielded between the first airflow and the second
21 airflow.

1 2. The electronic device as claimed in claim 1, wherein
2 temperature of the first heat source does not exceed that of
3 the second heat source.

1 3. The electronic device as claimed in claim 1, wherein
2 the first fan assembly is disposed near one side of the housing.

1 4. The electronic device as claimed in claim 1, wherein
2 the housing comprises an inlet, and the first fan assembly
3 is disposed between the inlet and the conductive assembly.

1 5. The electronic device as claimed in claim 1, wherein
2 the conductive assembly comprises a heat-transfer unit
3 connected to the first heat source.

1 6. The electronic device as claimed in claim 5, wherein
2 the heat-transfer unit comprises a fin structure.

1 7. The electronic device as claimed in claim 1, wherein
2 the first heat source comprises a CPU.

1 8. The electronic device as claimed in claim 1, wherein
2 the second heat source comprises a memory module.

1 9. The electronic device as claimed in claim 1, further
2 comprising a conductive pipe transferring heat from the
3 conductive assembly to one side of the first fan assembly.

1 10. The electronic device as claimed in claim 3, further
2 comprising a second fan assembly disposed on one side of the
3 housing conducting the second airflow to the surroundings.

1 11. The electronic device as claimed in claim 1, wherein
2 temperature of the first airflow is higher than that of the
3 second airflow.

1 12. A heat-dissipating module for providing heat
2 transfer and convection on at least one first heat source and
3 at least one second heat source located in a housing by an
4 initial airflow of a surroundings, comprising:

5 at least one conductive assembly disposed on the first
6 heat source to absorb heat transferring from the
7 first heat source;

8 at least one first fan assembly located between the
9 surroundings and the conductive assembly, wherein
10 the first fan assembly introduces the initial
11 airflow of the surroundings into the conductive
12 assembly to form at least one first airflow, and
13 the first airflow passes the second heat source to
14 form at least one second airflow, and temperature
15 ingredient is yielded between the first airflow and
16 the second airflow.

1 13. The heat-dissipating module as claimed in claim 12,
2 wherein temperature of the first heat source does not exceed
3 that of the second heat source.

1 14. The electronic device as claimed in claim 12,
2 wherein temperature of the first airflow is higher than that
3 of the second airflow.

1 15. The electronic device as claimed in claim 12,
2 wherein the housing comprises an inlet, and the first fan
3 assembly is disposed between the inlet and the conductive
4 assembly.

1 16. The electronic device as claimed in claim 12,
2 wherein the conductive assembly has a heat-transfer unit
3 connected to the first heat source.

1 17. The electronic device as claimed in claim 12,
2 wherein the first heat source comprises a CPU.

1 18. The electronic device as claimed in claim 12,
2 wherein the second heat source comprises a memory module.

1 19. The electronic device as claimed in claim 12,
2 further comprising a conductive pipe transferring heat from
3 the conductive assembly to one side of the first fan assembly.

1 20. The electronic device as claimed in claim 12,
2 further comprising a second fan assembly disposed on one side
3 of the housing conducting the second airflow to the
4 surroundings.